

IN THE CLAIMS:

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Claim 1 (currently presented): A capacitance type sensor comprising:

a substrate;

a group of fixed electrodes provided on an upper face of said substrate;

a movable electrode plate having an electrode on a lower flat face thereof, said movable electrode plate having a rubber elasticity; and wherein

said substrate is provided with at least a conductive solder layer having a thickness, in which said layer supports said movable electrode plate and said thickness of the layer provide a gap between said group of fixed electrodes on said substrate and said electrode on said movable electrode plate.

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Claim 2 (previously presented): A capacitance type sensor comprising:

a substrate;

a group of fixed electrodes provided on an upper face of said substrate;

a movable electrode plate having an electrode on a lower flat face thereof, said movable electrode plate having a rubber elasticity; and wherein

said substrate is provided with at least a layer of one of conductive elastomer, conductive paint and conductive adhesive material, said layer having a thickness in which said layer supports said movable electrode plate and said thickness of said layer provides a gap between said group of fixed electrodes on said substrate and said electrode on said movable electrode plate.

Claim 3 (original): A capacitance type sensor according to Claim 1, wherein said electrode on said movable electrode plate is made of one of conductive rubber plate and conductive elastomer plate.

Claim 4 (original): A capacitance type sensor according to Claim 2, wherein said electrode on said movable electrode plate is made of one of conductive rubber plate and conductive elastomer plate.